ESD Protection Diode

## DESCRIPTION

The ESD0501Q is designed for applications requiring transient overvoltage protection capability．They are intended for use in voltage and ESD sensitive equipment such as computers，printers，business machines， communication systems，medical equipment and other applications．These devices are ideal for situations where board space is at a premium．

This series has been specifically designed to protect sensitive components which are connected to power，data and transmission lines from overvoltage caused by ESD（electrostatic discharge），CDE（Cable Discharge Events），and EFT（electrical fast transients）．

## ORDERING INFORMATION

$\diamond$ Device：ESD0501Q
ヶPackage：DFN1006
$\triangleleft$ Marking：FQ
$\diamond$ Material：Halogen free
»Packing：Tape \＆Reel
$\triangleleft$ Quantity per reel：10，000pcs

PIN CONFIGURATION


## FEATURES

$\diamond$ Transient protection for high－speed data lines
IEC 61000－4－2（ESD）$\pm 15 \mathrm{kV}$（Air） $\pm 8 \mathrm{kV}$（Contact）
IEC 61000－4－4（EFT）40A（5／50 ns）
Cable Discharge Event（CDE）
$\diamond$ Package optimized for high－speed lines
$\diamond$ Ultra－small package（ $1.0 \mathrm{~mm} \times 0.6 \mathrm{~mm} \times 0.5 \mathrm{~mm}$ ）
$\diamond$ Protects one data，control line
$\diamond$ Low leakage current
২Low clamping voltage

## MACHANICAL DATA

$\diamond$ DFN1006 package
$\diamond$ Flammability Rating：UL 94V－0
$\diamond$ Packaging：Tape and Reel
$\checkmark$ High temperature soldering guaranted： $260^{\circ} \mathrm{C} / 10$ s
$\diamond$ Reel size： 7 inch

## APPLICATIONS

$\diamond$ Serial ATA
$\diamond$ Desktops，Servers and Notebooks
$\diamond$ Cellular Phones
«MDDI Ports
«USB Data Line Protection
$\diamond$ Display Ports
$\diamond$ Digital Visual Interfaces（DVI）

CIRCUIT DIAGRAM


時利
SHIKUES

## ABSOLUTE MAXIMUM RATING

| Symbol | Parameter | Value | Units |
| :---: | :--- | :---: | :---: |
| $\mathrm{V}_{\text {ESD }}$ | ESD per IEC 61000-4-2 (Air) |  |  |
| ESD per IEC 61000-4-2 (Contact) | $\pm 30$ <br> $\pm 30$ | kV |  |
| $\mathrm{P}_{\text {PP }}$ | Peak Pulse Power (8/20 $\mu \mathrm{s})$ | 240 | W |
| $\mathrm{~T}_{\text {OPT }}$ | Operating Temperature | $-55 \sim 125$ | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\text {STG }}$ | Storage Temperature | $-55 \sim 150$ | ${ }^{\circ} \mathrm{C}$ |

## ELECTRICAL CHARACTERISTICS (Tamb=25 ${ }^{\circ} \mathrm{C}$ )

| Symbol | Parameter | Test Condition | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {RWM }}$ | Reverse Working Voltage |  |  |  | 5 | V |
| $V_{\text {BR }}$ | Reverse Breakdown Voltage | $\mathrm{I}_{\mathrm{T}}=1 \mathrm{~mA}$ | 6 |  |  | V |
| $I_{R}$ | Reverse Leakage Current | $\mathrm{V}_{\text {RWm }}=5 \mathrm{~V}$ |  |  | 1 | $\mu \mathrm{A}$ |
| $V_{\text {F }}$ | Forward Voltage | $\mathrm{I}_{\mathrm{F}}=10 \mathrm{~mA}$ |  |  | 1.0 | V |
| $\mathrm{V}_{\mathrm{c}}$ | Clamping Voltage | $\mathrm{I}_{\mathrm{PP}}=1 \mathrm{~A}, \mathrm{t}_{\mathrm{p}}=8 / 20 \mu \mathrm{~s}$ |  |  | 8 | V |
|  |  | $\mathrm{l}_{\mathrm{PP}}=15 \mathrm{~A}, \mathrm{t}_{\mathrm{p}}=8 / 20 \mu \mathrm{~s}$ |  |  | 16 | V |
| C J | Junction Capacitance | $\mathrm{V}_{\mathrm{R}}=0 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ |  | 130 |  | pF |



## DFN1006 PACKAGE OUTLINE DIMENSIONS




|  | MIN | NOM | MAX |
| :---: | :---: | :---: | :---: |
| D | 0.55 | 0.60 | 0.65 |
| E | 0.95 | 1.00 | 1.05 |
| L1 | 0.20 | 0.25 | 0.30 |
| L2 | 0.20 | 0.25 | 0.30 |
| b | 0.45 | 0.50 | 0.55 |
| e | 0.65 BSC |  |  |
| A | 0.45 | 0.50 | 0.55 |
| h | 0.07 | 0.12 | 0.17 |

Dimension: Millimeter
(Stencil thickness: 0.1 )


Soldering Footprint

